

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
Contact Info: ti.com/support  
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
Created on: 06/06/2022

Details for "SN74AXC1T45QDCKRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
SN74AXC1T45QDCKRQ1	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	CDK   6	2x1.3x0.9	12.4

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.016729	97.386192	973862	0.134652	1347
Precious Metals	Gold	7440-57-5	0.000037	0.215392	2154	0.000298	3
Precious Metals	Palladium	7440-05-3	0.000412	2.398417	23984	0.003316	33
Sub-Total			0.017178	100	1000000	0.138266	1383
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.030585	80.000523	800005	0.246179	2462
Thermoplastics	Epoxy	85954-11-6	0.007646	19.999477	199995	0.061543	615
Sub-Total			0.038231	100	1000000	0.307721	3077
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	7.791702	97.444997	974450	62.715402	627154
Copper and Its Alloys	Iron	7439-89-6	0.187906	2.35	23500	1.512455	15125
Copper and Its Alloys	Phosphorus	7723-14-0	0.006397	0.080003	800	0.051489	515
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0004	0.005003	50	0.00322	32
Zinc and Its Alloys	Zinc	7440-66-6	0.009595	0.119997	1200	0.07723	772
Sub-Total			7.996	100	1000000	64.359797	643598
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.466088	95.12	951200	3.751542	37515
Precious Metals	Gold	7440-57-5	0.003822	0.78	7800	0.030763	308
Precious Metals	Palladium	7440-05-3	0.02009	4.1	41000	0.161704	1617
Sub-Total			0.49	100	1000000	3.94401	39440
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	3.298098	86.850014	868500	26.546388	265464
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	0.018987	0.499992	5000	0.152826	1528
Other Plastics and Rubber	Carbon Black	1333-86-4	0.005696	0.149995	1500	0.045847	458
Thermoplastics	Epoxy	85954-11-6	0.474683	12.5	125000	3.820723	38207
Sub-Total			3.797464	100	1000000	30.565784	305658
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.085032	100	1000000	0.684422	6844
Sub-Total			0.085032	100	1000000	0.684422	6844
Total			12.423905			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."  
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
For further environmental statements, please go to [www.ti.com/ecoinfo](#)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in [http://www.ti.com/lit/pdf/szzq088](#)

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.